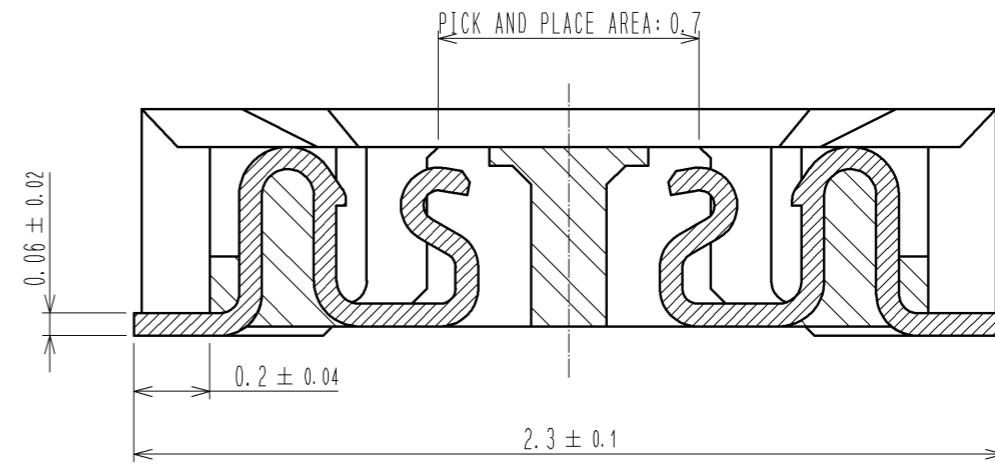
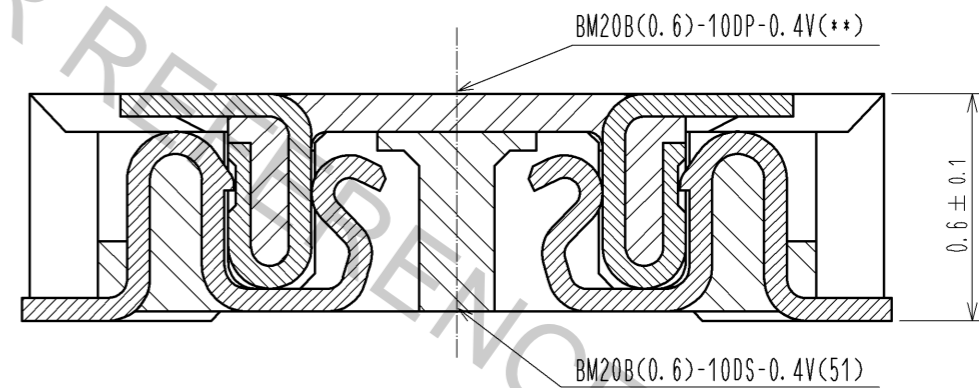


A-A(50:1)



ENGAGEMENT FIGURE (50:1)



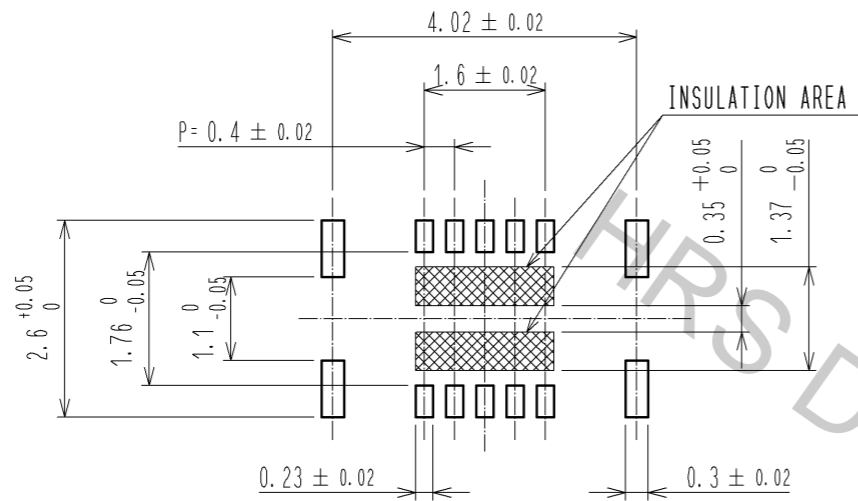
- NOTE
- 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
 - 2 CONTACT PLATING SPECIFICATIONS
 CONTACT AREA : GOLD 0.05 μm MIN
 SMT LEAD : GOLD 0.05 μm MIN
 UNDERPLATING : NICKEL 1 μm MIN
 (SURFACE : SEALING)
 - 3 METAL FITTING PLATING SPECIFICATIONS
 SMT LEAD : GOLD 0.05 μm MIN
 UNDERPLATING : NICKEL 1 μm MIN
 (SURFACE : SEALING)
 - 4 HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.

| NO. | MATERIAL | FINISH . REMARKS | NO. | MATERIAL | FINISH . REMARKS |
|-----|-----------------|-------------------------------|-----|-----------|------------------------------|
| 4 | PS | CLEAR (EMBOSSED CARRIER TAPE) | 7 | PS | CLEAR (REINFORCEMENT COLLAR) |
| 3 | BRASS | 3 | 6 | PS | BLACK (PLASTIC REEL) |
| 2 | PHOSPHOR BRONZE | 2 | 5 | POLYESTER | CLEAR (COVER TAPE) |
| 1 | LCP | UL94 V-0, BLACK | | | |

| UNITS | SCALE | COUNT | DESCRIPTION OF REVISIONS | DESIGNED | CHECKED | DATE |
|-------|-------|-------|--------------------------|-------------|-------------|----------|
| mm | 10:1 | 1 | DIS-H-007926 | Hongwoo. Jo | WR. FUKUCHI | 13.05.30 |

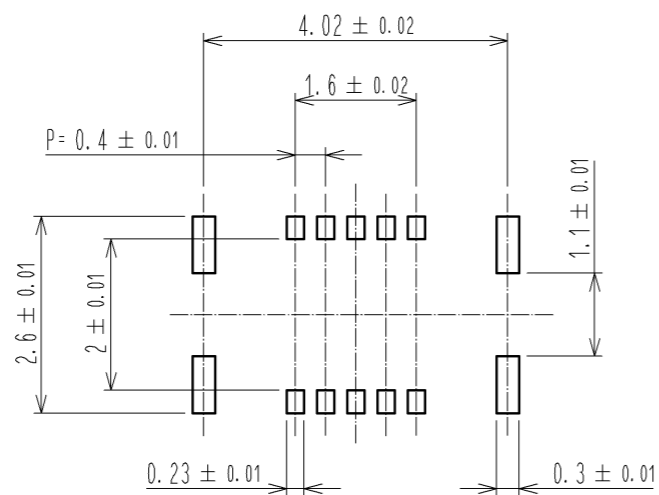
| APPROVED | DATE | DRAWING NO. |
|-------------|----------|--------------------------|
| KH. IKEDA | 12.11.05 | EDC3-347095-51 |
| CHECKED | DATE | PART NO. |
| WR. FUKUCHI | 12.11.05 | BM20B(0.6)-10DS-0.4V(51) |
| DESIGNED | DATE | CODE NO. |
| RT. SHIMIZU | 12.11.05 | CL684-9308-8-51 |
| DRAWN | DATE | |
| RT. SHIMIZU | 12.11.05 | |

◆ RECOMMENDED PCB LAYOUT

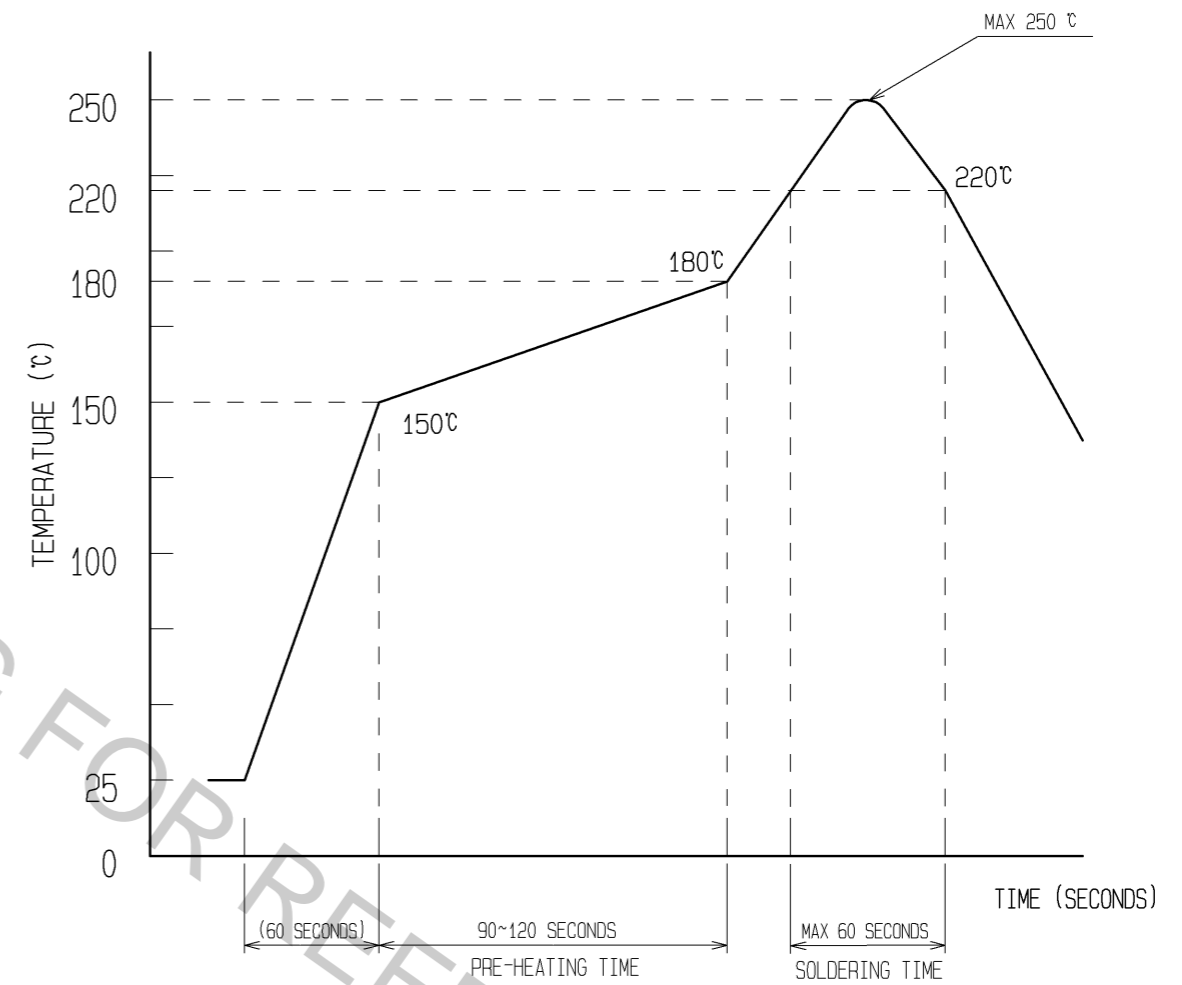


◆ RECOMMENDED METAL MASK DIMENSIONS

MATAL MASK THICKNESS : 100 μm



5 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



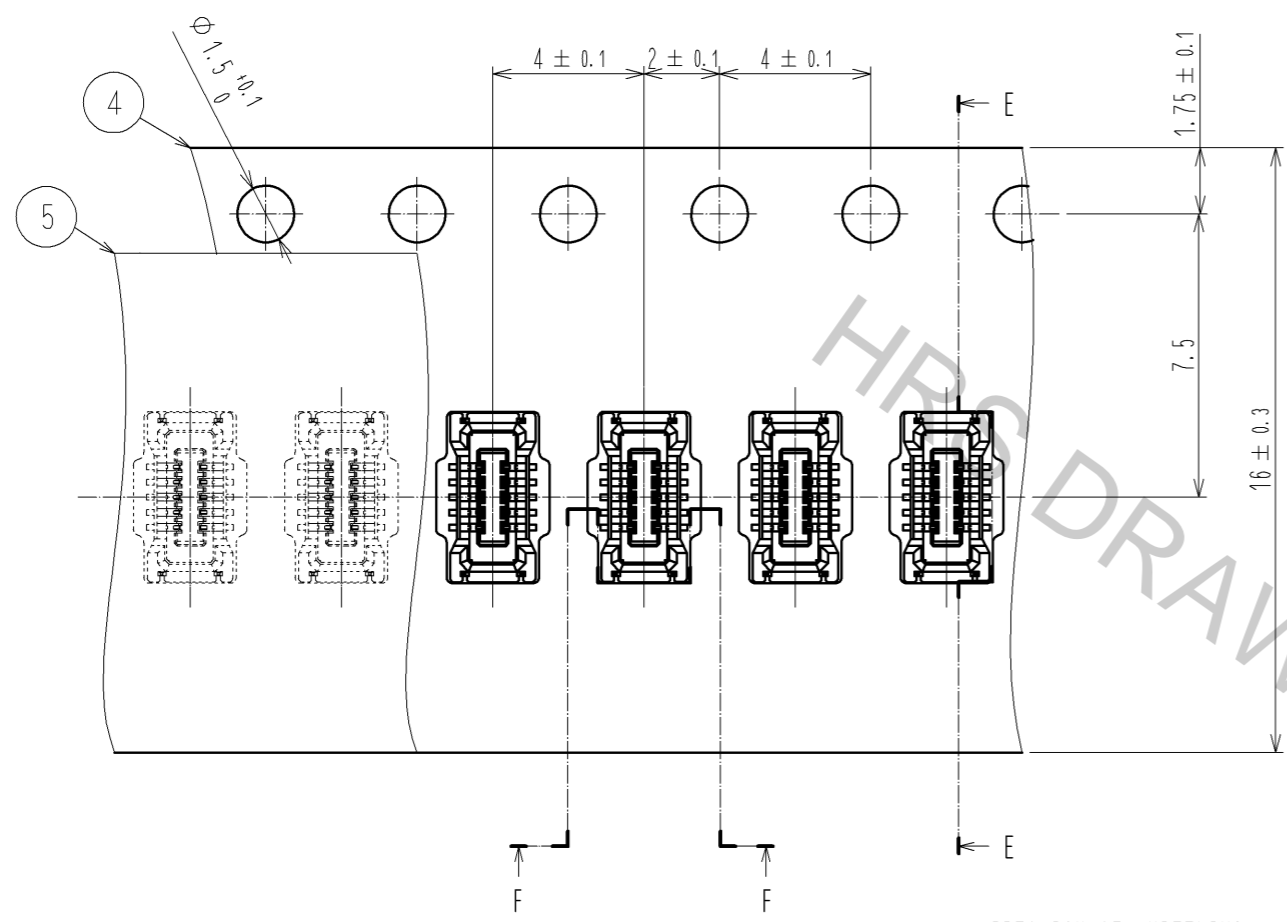
- REFLOW METHOD : IR REFLOW
 NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
 1) REFLOW TIME
 DURATION ABOVE 220°C, 60 SEC MAX.
 (PEAK TEMPERATURE : 250°C MAX)
 2) PRE-HEAT TIME
 PRE-HEAT TEMPERATURE(MIN): 150°C
 PRE-HEAT TEMPERATURE(MAX): 180°C
 PRE-HEAT TIME: 90-120 SEC.

5 THE TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

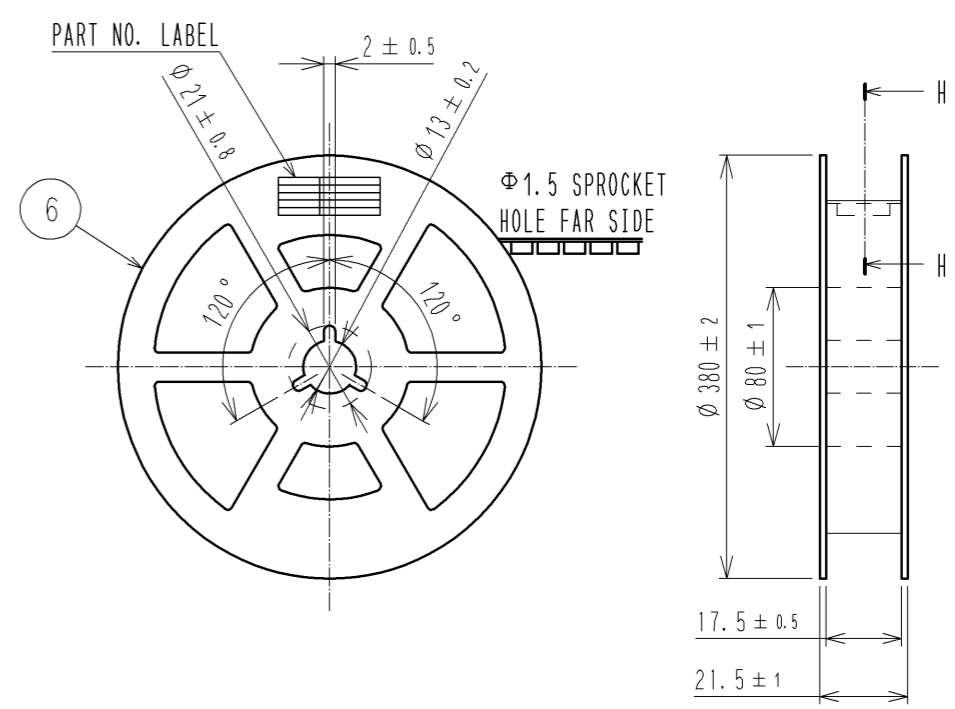
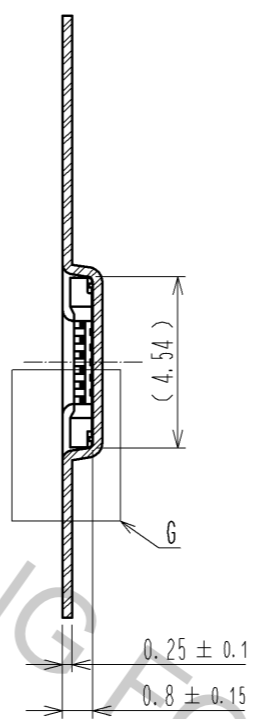
| | | |
|------------|-------------|--------------------------|
| HRS | DRAWING NO. | EDC3-347095-51 |
| | PART NO. | BM20B(0.6)-10DS-0.4V(51) |
| | CODE NO. | CL684-9308-8-51 |
| | | 2/3 |

EMBOSSED CARRIER TAPE PACKAGING (5:1)

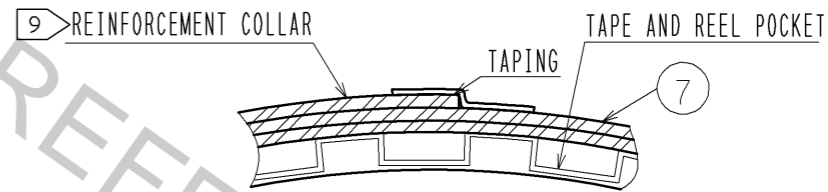
STYLE AND DIMENTION OF REEL (FREE)



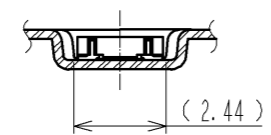
E-E (5:1)



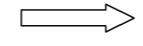
H-H (FREE)



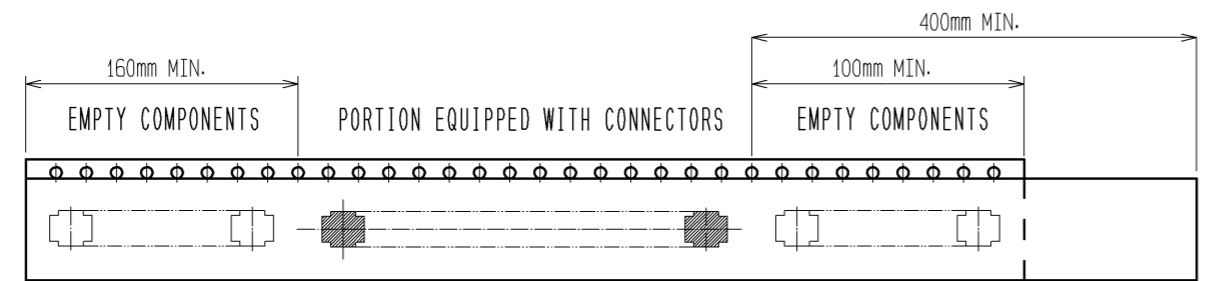
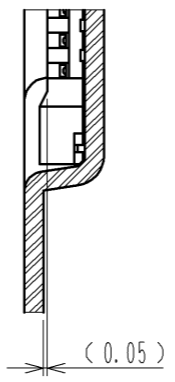
F-F (5:1)



DIRECTION OF UNREELING



G(10:1)



DETAIL OF PART NO. LABEL

| | |
|-------|--------------------------|
| 製造年月日 | ** ** * |
| 製品コード | CL0684-9308-8-51 |
| 製品名 | BM20B(0.6)-10DS-0.4V(51) |
| 数量 | 8,000 |
| 納入者 | ヒロセ電機(株) |

DATA OF MANUFACTURED
CODE NO.
PART NO.
QUANTITY
SUPPLIER

- 6. PER REEL 8000 CONNECTORS.
- 7. THE DIMENSIONS IN PARENTHESSES ARE FOR REFERENCE.
- 8. REFER TO JIS C 0806(PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING)
- 9. AFTER PACKAGING, ROLL 2 METERS OF THE REINFORCEMENT COLLAR TO OUTER CIRCUMFERENCE OF TAPE AND REEL POCKET. AND TAPE DOWN AT THE END THE COLLAR.

| | | |
|------------|-------------|--------------------------|
| HRS | DRAWING NO. | EDC3-347095-51 |
| | PART NO. | BM20B(0.6)-10DS-0.4V(51) |
| | CODE NO. | CL684-9308-8-51 |
| | | 3/3 |

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